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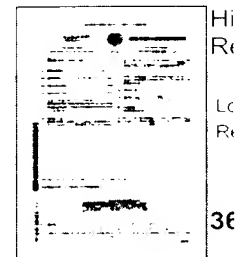
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Get Now: ☐ PDF | [More choices](#)Tools: [Add to Work File](#) | [Create new Work File](#)View: [Expand Details](#) | [INPADOC](#) | Jump to: [Top](#)[Go to: Derwent](#)[Email this](#)Title: **WO0188482A1: SENSOR ELEMENT AND ITS MANUFACTURING METHOD**Country: **WO** World Intellectual Property Organization (WIPO)Kind: **A1** Publ. of the Int. Appl. with Int. search reportInventor: **YASUDA, Naoki**; Mitsubishi Denki Kabushiki Kaisha, 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310, Japan**FUKAMI, Tatsuya**; Mitsubishi Denki Kabushiki Kaisha, 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310, Japan**TAGUCHI, Motohisa**; Mitsubishi Denki Kabushiki Kaisha, 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310, Japan**KAWANO, Yuji**; Mitsubishi Denki Kabushiki Kaisha, 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310, JapanAssignee: **MITSUBISHI DENKI KABUSHIKI KAISHA**, 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310, Japan[News](#), [Profiles](#), [Stocks](#) and [More](#) about this companyPublished / Filed: **2001-11-22 / 2000-05-15**Application Number: **WO2000JP0003077**IPC Code: **G01D 21/00**; H01L 43/12; G01F 1/68; G01P 15/08; G01R 33/06; G01L 9/00; H01L 29/84;ECLA Code: **G01F1/684M**;Priority Number: 2000-05-15 **WO2000000003077**

Abstract:

A sensor element is provided with a sensor substrate and a sensing portion supported by the substrate, wherein a resin film is formed between the sensor substrate and the sensing member. The resin film has heat resistance against manufacturing process temperatures and use temperatures and excellent coverage of the underlying surface having a three-dimensional structure. The surface can be planarized. The stress on the sensing portion is little. The resin film can be formed at a low temperature, which prevents bad influence on the sensing portion during the manufacturing process.

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(12)特許協力条約に基づいて公開された国際出願

(19) 世界知的所有権機関
国際事務局



(43) 国際公開日
2001年11月22日 (22.11.2001)

PCT

(10) 国際公開番号
WO 01/88482 A1

(51) 国際特許分類: G01D 21/00, H01L 43/12, G01F 1/68,
G01P 15/08, G01R 33/06, G01L 9/00, H01L 29/84

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(21) 国際出願番号: PCT JP00/03077

(22) 国際出願日: 2000年5月15日 (15.05.2000)

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(25) 国際出願の言語: 日本語

(26) 国際公開の言語: 日本語

(81) 指定国 (国内): JP, KR, US.

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(84) 指定国 (広域): ヨーロッパ特許 (AT, BE, CH, CY, DE,
DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

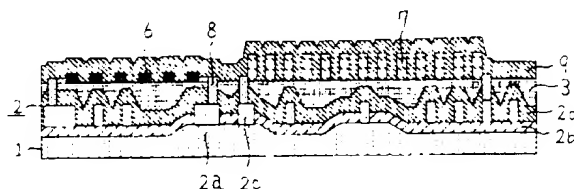
添付公開書類:
国際調査報告書

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2文字コード及び他の略語については、定期発行される
各PCTガゼットの巻頭に掲載されている「コードと略語
のガイダンスノート」を参照。

(54) Title: SENSOR ELEMENT AND ITS MANUFACTURING METHOD

(54) 発明の名称: センサ素子及びその製造方法



(57) Abstract: A sensor element is provided with a sensor substrate and a sensing portion supported by the substrate, wherein a resin film is formed between the sensor substrate and the sensing member. The resin film has heat resistance against manufacturing process temperatures and use temperatures and excellent coverage of the underlying surface having a three-dimensional structure. The surface can be planarized. The stress on the sensing portion is little. The resin film can be formed at a low temperature, which prevents bad influence on the sensing portion during the manufacturing process.

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